

Filename: PMP8714RevA - BoM.xls

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## PMP8714 Rev.A - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	100nF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	TDK
1	C2	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	C1608X7R1C105K	TDK
1	C6	100pF	Capacitor, Ceramic, 100V, X7R	0603	Std	Std
1	C9	56pF	Capacitor, Ceramic, 50V, NP0/C0G	0603	Std	TDK
1	C12	22nF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	TDK
2	C10 C101	10nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	TDK
2	C13-14	100nF	Capacitor, Ceramic, 100V, X7R	0805	C2012X7R2A104M	TDK
2	C3-4	100uF	Capacitor, Ceramic, 6.3V, X5R, 15%	1210	C3225X5R0J107K	TDK
2	C7-8	4.7uF	Capacitor, Ceramic, 50V, 4.7-uF, X7R, 15%	1210	C3225X7R1H475K	TDK
1	D2	B260	Diode, Schottky, 2A, 60V	SMB	B260	Diodes Inc.
2	J1-2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	L1	3.3uH	Inductor, SMT, 3.94Arms, 18.3-milliohm	0.300 sq"	DR74-3R3-R	Coiltronics
1	L2	33uH	Inductor, SMT, 1.66A, 84milliohm	0.402 x 0.394 inch	MSS1048-333L	Coilcraft
1	R1	24.3K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	10	Resistor, Chip, 1/10W, yy%	0805	Std	Std
1	R8	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	31.6K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	10K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	86.6K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R100	1Meg	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R3 R12	348K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	TP10	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
2	TP13-14	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TPS54160A	IC,DC-DC Converter, 3V-60V, 1.5A	MSOP-10	TPS54160A	Texas Instruments

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